

COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

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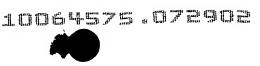
My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

BUMP LAYOUT ON SILICON CHIP

the	specification of whic	ch control				
X	is attached hereto					
	was filed on					
	as Application Ser	ial No	and was amended on_		··	
app app fore	cification, including to a cknowledge the lication in accordance I hereby claim fore lication(s) for paten	the claims, as amended to duty to disclose inforce with Title 37, Code control of the control of	nd understand the content of by any amendment referred that it is material to be federal Regulations, § 1. It der Title 35, United States Cate listed below and have ficate having a filing date be	ed to above. the paten .56(a). Code, § 119 also identif	tability of this of any foreign fied below any	
	Number	Country	Date Filed(yyyy/mm/dd)	Yes	No	
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:	SEND CORRESPO	NDENCE TO:		DIRECT TELEPHONE CALLS TO: (Name and telephone number)		
JIANQ CHYUN Intellectual Property Office 7F-1 No. 100 Roosevelt Rd. Sec. 2 Relinda Lee						

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Date: 2002-07-11

COMBINED DECLARATION AND POWER OF AT 1 DRNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

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